

REMARKS/ARGUMENT

Claims 1-11 are pending in this application. By this Amendment, claims 1 and 11 have been amended. The amendments made to claims 1 and 11 do not alter the scope of these claims, nor have these amendments been made to define over the prior art. Rather, the amendments have been made to improve the form thereof. In light of the amendments and remarks set forth below, Applicant respectfully submits that each of the pending claims is in immediate condition for allowance.

The amendments to the claims are for clarification purposes only and are not intended to limit the scope of the claims in any way. It is asserted that the present amendment places the application in a form for allowance. Entry of this amendment is therefore earnestly solicited.

Notice of Allowance for all of the pending claims is therefore respectfully requested.

Application No.: 09/872,256

Docket No.: H2041.0061/P061

If the Examiner believes an interview would be of assistance, the Examiner is welcome to contact the undersigned at the number listed below.

Dated: June 26, 2003

Respectfully submitted,


By _____

Ian R. Blum

Registration No.: 42,336

DICKSTEIN SHAPIRO MORIN &
OSHINSKY LLP

1177 Avenue of the Americas - 41st Floor

New York, New York 10036-2714

(212) 835-1400

Attorney for Applicant

IRB/mgs

APPENDIX A
Complete Set of Claims Pursuant to 37 CFR § 1.125

Claim 1. (Currently and Previously Amended) A mounting structure of a printed circuit board for establishing electrical connection to a semiconductor package, said mounting structure comprising:

a pad formed on a first surface of said printed circuit board;

a connection wiring formed on a second surface opposite to said first surface;

a plating, said plating covering said pad entirely and extending to the surface of said printed circuit board; and

a via formed through said printed circuit board, said via providing electrical communication between said pad and said connection wiring.

c1
Claim 2. (Previously Amended) A mounting structure as in claim 1, wherein said via has an annular shape on said printed circuit board for establishing said electrical communication.

Claim 3. (Previously Amended) A mounting structure as in claim 1, wherein a plating is provided on the surface of said pad and an inner surface of said via.

Claim 4. (Previously Amended) A mounting structure as in claim 1, wherein said via is formed in said pad of said printed circuit board corresponding to a corner of said semiconductor package.

Claim 5. (Previously Amended) A mounting structure as in claim 1, wherein said via has a truncated cone shape for providing said electrical communication.

Claim 6. (Previously Amended) A mounting structure as in claim 3, wherein said via has a truncated cone shape for providing said electrical communication.

Claim 7. (Previously Amended) A mounting structure as in claim 2, wherein a space is provided between an outer circumference of said pad and a solder resist on said printed circuit board.

Claim 8. (Previously Amended) A mounting structure as in claim 2, wherein a plating is provided on the surface of said pad and an inner surface of said via.

cl
cont
Claim 9. (Previously Amended) A mounting structure as in claim 2, wherein said via has a truncated cone shape for providing said electrical communication.

Claim 10. (Previously Amended) A mounting structure as in claim 8, wherein said via has a truncated cone shape for providing said electrical communication.

Claim 11. (Currently and Previously Amended) A mounting structure of a semiconductor package in which a semiconductor package is mounted by soldering on a pad of a printed circuit board for electrical connection with a connection wiring, characterized in that
a via is formed through an entire thickness of said printed circuit board,
said pad is integrated with said via on one surface of said printed circuit board,
a plating, said plating covering said pad entirely and extending to the surface of
said printed circuit board;

said pad and said semiconductor package are connected to said via on one surface of said printed circuit board by penetrating a pair into said via or by soldering, and

said connection wiring is connected to said via on the other surface of said printed circuit board.